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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# SS12, SS14

## Surface Mount Schottky Power Rectifier

### SMA Power Surface Mount Package

These devices employ the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

#### Features

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Stress Protection
- Pb-Free Packages are Available

#### Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm tape, 5000 units per 13 inch reel
- Polarity: Cathode Lead Indicated by Polarity Band
- Device Meets MSL 1 Requirements
- ESD Ratings: Human Body Model, 3B (> 8000 V)  
Machine Model, B (> 200 V)



**ON Semiconductor®**

<http://onsemi.com>

**SCHOTTKY BARRIER  
RECTIFIER  
1.0 AMPERES  
20, 40 VOLTS**



**SMA  
CASE 403D  
PLASTIC**

#### MARKING DIAGRAM



SS1x = Specific Device Code  
x = 2 or 4  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

#### ORDERING INFORMATION

Device	Package	Shipping†
SS12T3	SMA	5000/Tape & Reel
SS12T3G	SMA (Pb-Free)	5000/Tape & Reel
SS14T3	SMA	5000/Tape & Reel
SS14T3G	SMA (Pb-Free)	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# SS12, SS14

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	20 40	V
Average Rectified Forward Current (At Rated $V_R$ , $T_C = 120^\circ\text{C}$ )	$I_O$	1.0	A
Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 20 kHz, $T_C = 120^\circ\text{C}$ )	$I_{FRM}$	2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	60	A
Storage/Operating Case Temperature	$T_{stg}, T_C$	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature	$T_J$	-55 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	$dv/dt$	10,000	$\text{V}/\mu\text{s}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	$R_{\theta JL}$	35	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	86	$^\circ\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2) see Figure 2 for other Values $(I_F = 1.0 \text{ A})$	$V_F$	$T_J = 25^\circ\text{C}$		V
		0.47		
Maximum Instantaneous Reverse Current see Figure 4 for other Values $(V_R = 20 \text{ V})$ $(V_R = 40 \text{ V})$	$I_R$	$T_J = 25^\circ\text{C}$	$T_J = 100^\circ\text{C}$	mA
		0.045 0.1	2.0 5.0	

- Mounted on 2 in Square PC Board with 1 in Square Total Pad Size, PC Board FR4.
- Pulse Test: Pulse Width  $\leq 250 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

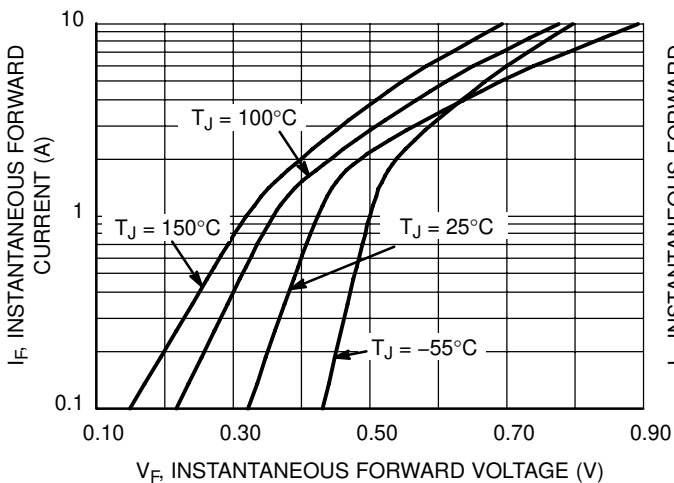


Figure 1. Typical Forward Voltage

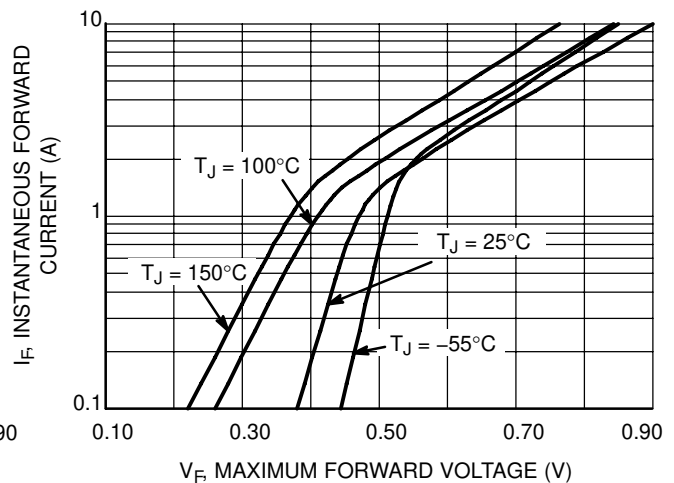


Figure 2. Maximum Forward Voltage

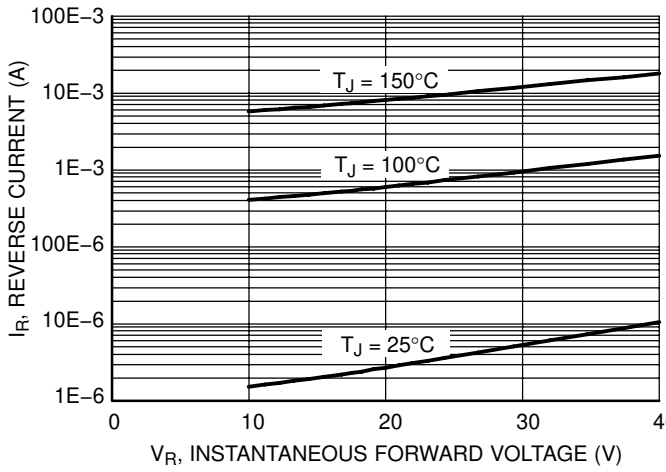


Figure 3. Typical Reverse Current

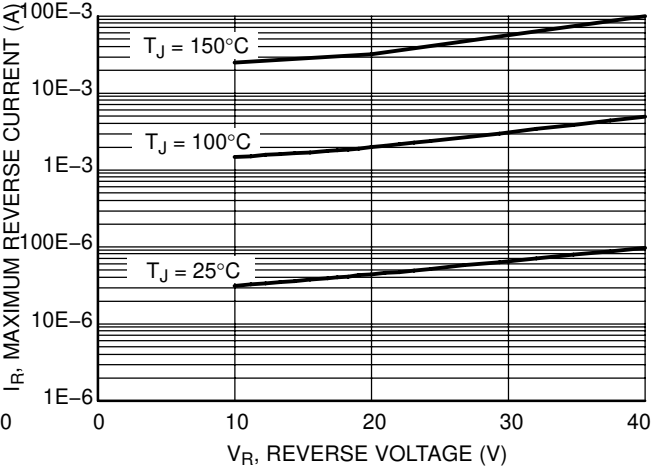


Figure 4. Maximum Reverse Current

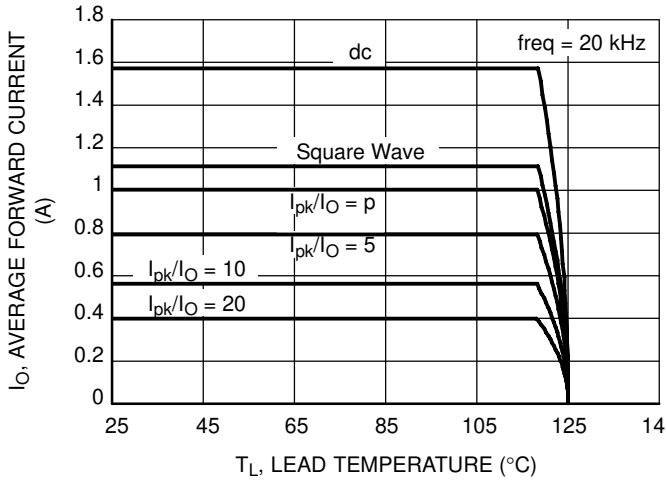


Figure 5. Current Derating

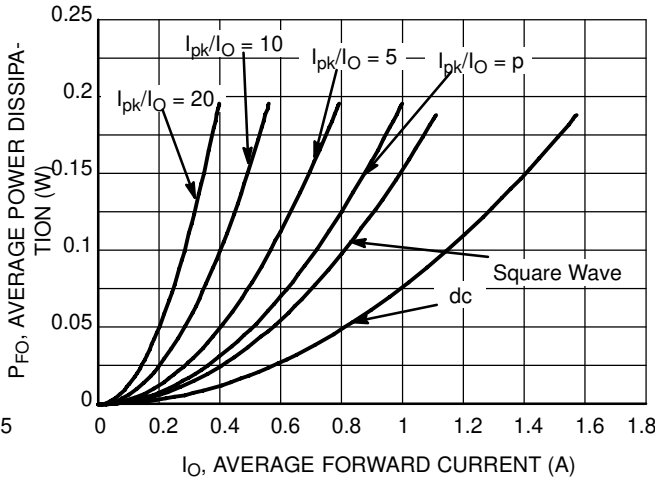


Figure 6. Forward Power Dissipation

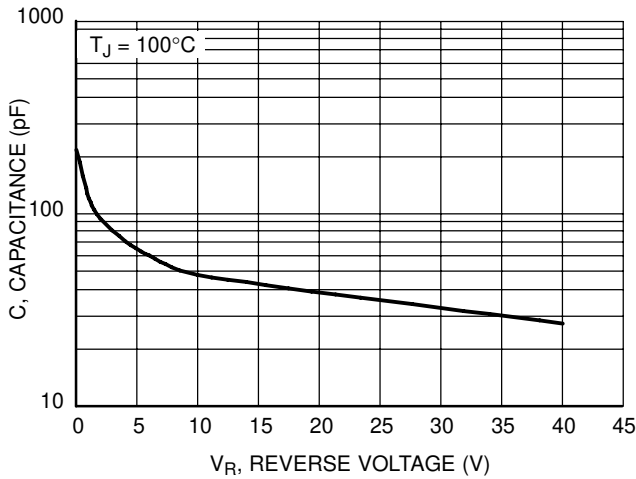


Figure 7. Capacitance

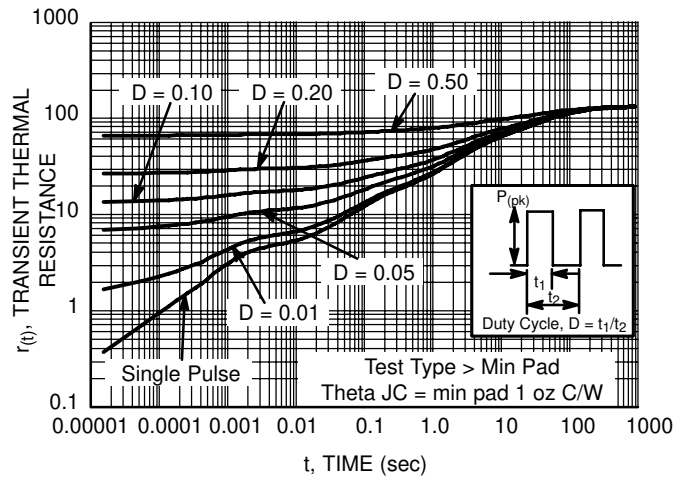
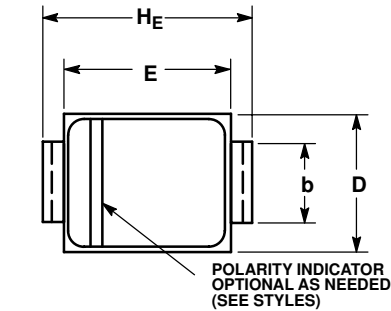


Figure 8. Thermal Response

# SS12, SS14

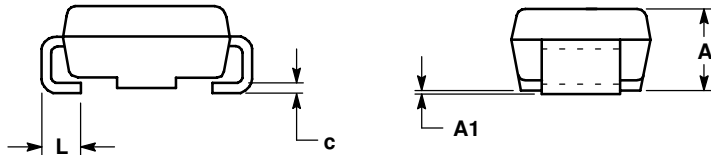
## PACKAGE DIMENSIONS

### SMA CASE 403D-02 ISSUE C



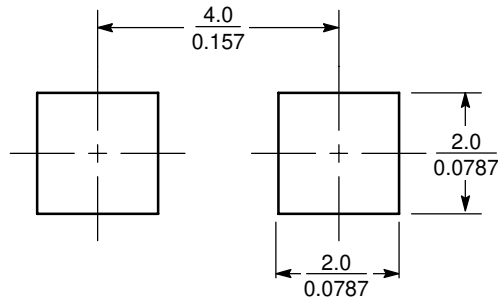
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.91	2.16	2.41	0.075	0.085	0.095
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	1.27	1.45	1.63	0.050	0.057	0.064
c	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060



- STYLE 1:  
PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

### SOLDERING FOOTPRINT\*



SCALE 8:1 ( $\frac{\text{mm}}{\text{inches}}$ )

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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